PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCI No.	CRP/24/13832
1.3 Title of PCI	D2PAK/H2PAK Carrier tape design robustness improvement
1.4 Product Category	Refer to impacted product list
1.5 Issue date	2024-03-05

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Process Owner	Chiara ZACCHERINI
2.1.2 Corporate Quality Manager	Gerard PETIT

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any indirect material modifications for shipping products in dimensions, material, composition, orientation	ST Shenzhen

4. Description of change

	Old	New
4.1 Description	Carrier tape current design (refer to detailed description with schematic)	Carrier tape new design (refer to detailed description with schematic) : - Add a platform on the pocket bottom : it will have the better strength than the flat bottom pocket - Increase the thickness of the carrier tape from T=0.30mm to T=0.35mm
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Form : No change on product Fit : No change on product Function : No change on product Reliability : No change on product Processability : No change on product	

5. Reason / motivation for change

5.1 Motivation	For quality continuous improvement, the design of the carrier tape is enhanced to prevent lead deformation.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Date-code - Internal Traceability

7. Timing / schedule

7.1 Date of qualification results	2024-01-02
7.2 Intended start of delivery	2024-06-03
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13832 PCI D2PAK-H2PAK Carrier tape design robustness improvement_W07.pdf

8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2024-03-05

9. Attachments (additional documentations)
13832 Public product.pdf 13832 PCI D2PAK-H2PAK Carrier tape design robustness improvement_W07.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	L7824CD2T-TR	
	STB10N60M2	
	STB12NM50T4	
	STB13N80K5	
	STB140NF75T4	
	STB20N65M5	
	STB23N80K5	
	STB30N65M5	
	STB7NK80ZT4	
	STGB40H65FB	
	STPS20150CG-TR	
	STPS20M100SG-TR	
	STPS30170CG-TR	
	STTH2003CG-TR	
	STTH8L06G-TR	
	STTH8R06G-TR	
	LM317D2T-TR	
	VNB20N07TR-E	

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